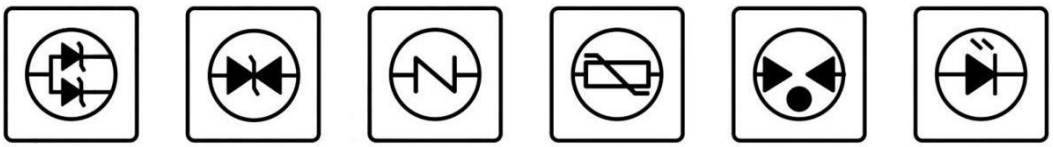
MSKSEMI 美森科
SEMICONDUCTOR



MEL357X

产品手册

描述

MEL357X 是一块小外形的贴片光电耦合器件，适合表面贴装生产。 MEL357X 是由一个砷化镓发光二极管和一个光电晶体管组成的光电耦合器，它的体积比 DIP 小，适用于高密度表面贴装应用，如可编程控制器等。

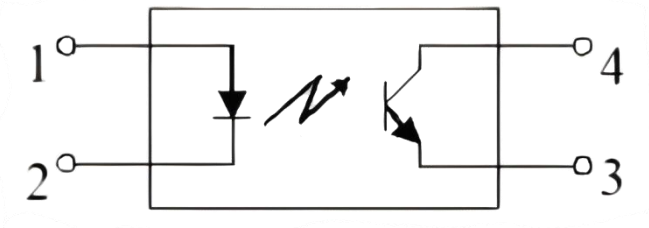
特性

- 电流转换比 (CTR)范围: 50~600%（I_F =5mA ,V_{CE} =5V）
- 输入-输出隔离电压 (Viso=3750 Vrms)
- 集电极-发射极击穿电压 BV_{CEO}≥80V

应用领域

- 开关电源，智能电表
- 工业控制，测量仪器
- 办公设备， 比如复印机
- 家用电器， 比如空调、风扇、热水器等

封装信息及内部引脚配置

封装	引脚配置
	
SOP-4	

订单信息

型号	封装	最小包装
MEL357X	SOP-4	3000

极限参数 (Ta=25℃)

参数		符号	额定值	单位
输入	正向电流	I_F	50	mA
	正向脉冲电流	I_{FP}	1	A
	反向电压	V_R	6	V
	功耗	P	70	mW
	结温	Tj	125	℃
输出	集电极功耗	P_C	150	mW
	集电极电流	I_C	50	mA
	集电极-发射极电压	V_{CEO}	80	V
	发射极-集电极电压	V_{ECO}	7	V
	结温	Tj	125	℃
总功耗		Ptot	200	mW
隔离电压		Viso	3750	Vrms
工作温度		Topr	-55~+110	℃
储存温度		Tstg	-55~+125	℃
焊接温度		Tsol	260	℃

CTR 分级表

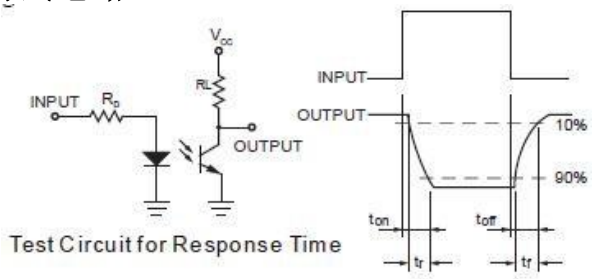
型号	管体标记	分级标准	I_C(mA)		对应CTR (%)	
			I_F = 5mA, V_{CE} = 5V, Ta = 25°C		I_F = 5mA, V_{CE} = 5V, Ta = 25°C	
			Min	Max	Min	Max
MEL357	MSK EL357 MS***	Blank	2.5	30.0	50	600
MEL357A	MSK EL357A MS***	A	4.0	8.0	80	160
MEL357B	MSK EL357B MS***	B	6.5	13.0	130	260
MEL357C	MSK EL357C MS***	C	10.0	20.0	200	400
MEL357D	MSK EL357D MS***	D	15.0	30.0	300	600

光电特性（Ta=25℃）

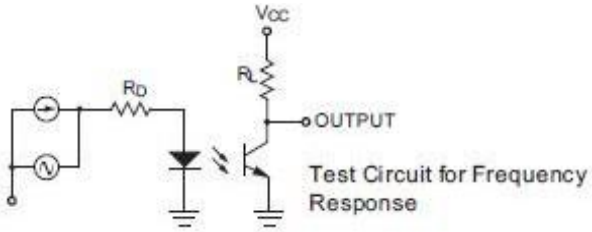
Parameter		Symbol	Condition	Min.	Typ.	Max.	Unit
输入	正向电压	V_F	I_F=20mA		1.2	1.4	V
	反向电流	I_R	V_R=5V	-	-	10	μA
	终端电容	C_t	V=0, f= 1kHz	-	30	250	pF
输出	集电极暗电流	I_{CEO}	V_{CE}=70V	-	-	100	nA
	集电极-发射极击穿电压	BV_{CEO}	I_C=0. 1mA, I_F=0	80	-	-	V
	发射极-集电极击穿电压	BV_{ECO}	I_E=0. 1mA, I_F=0	7	-	-	V
传输特性	电流转换比	CTR	I_F=5mA, V_{CE}=5V	50	-	400	%
	集电极-发射极饱和压降	$V_{CE(sat)}$	I_F=20mA, I_C= 1mA	-	0.1	0.2	V
	隔离电阻	R_{ISO}	DC1000V, 40~60%R.H.	$1x10^{11}$	-	-	Ω
	隔离电容	Cf	V=0, f= 1MHz	-	0.6	1.0	pF
	集电极-发射极电容	C_{CE}	V=0, f= 1MHz		10		pF
	截止频率	Fc	V_{CE}=5V, I_C=2mA, R_L= 100Ω, -3dB	-	80	-	kHz
开关时间	上升时间	Tr	V_{CE}= 10V, I_C=2mA, R_L= 100Ω	-	4	18	μs
	下降时间	Tf		-	3	18	μs

* CTR=I_C/I_F x 100%

测试电路

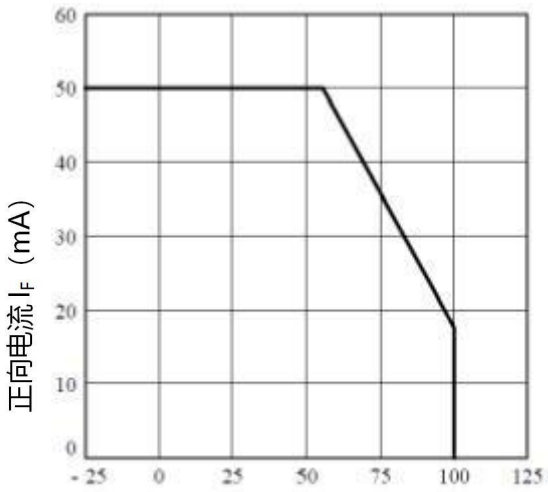


Test Circuit for Response Time

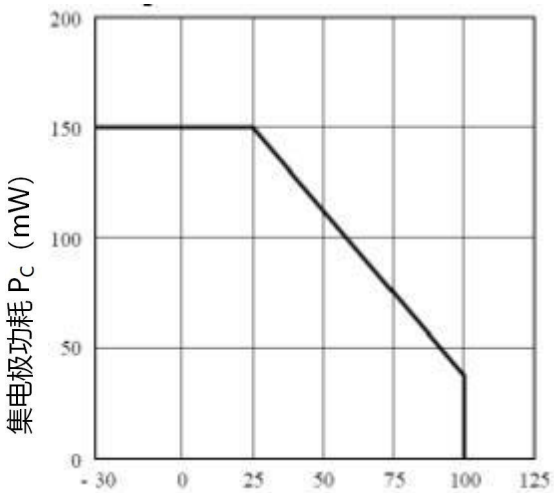


Test Circuit for Frequency Response

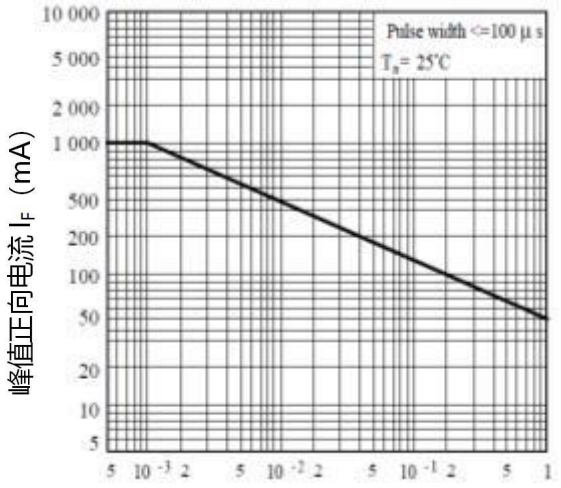
I_F-Ta



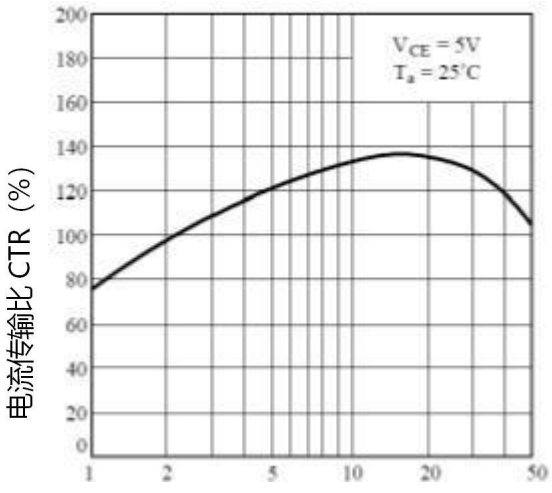
P_C-Ta



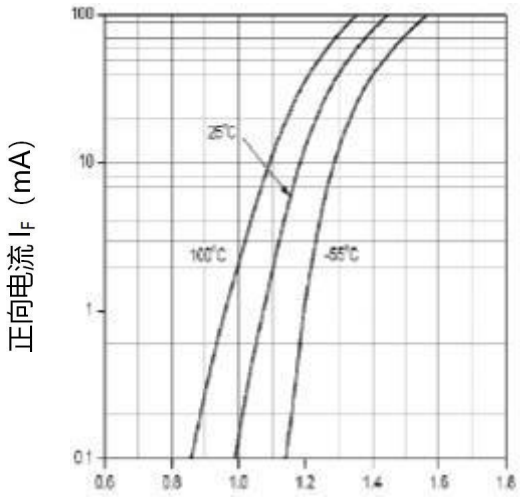
I_{FM}-D_R



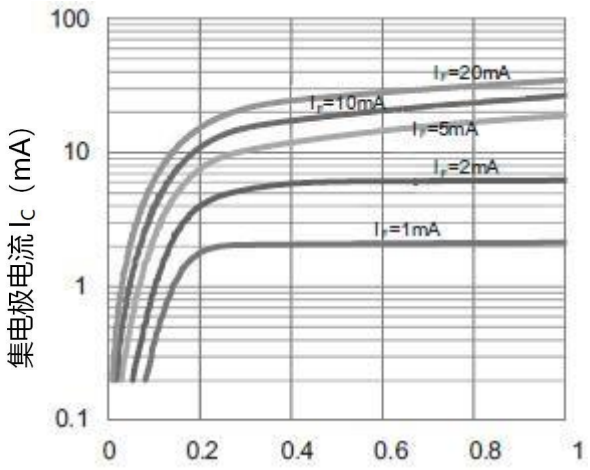
CTR- I_F



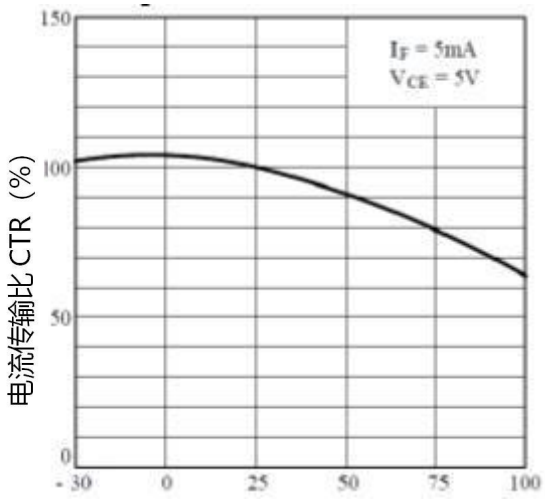
I_F-V_F



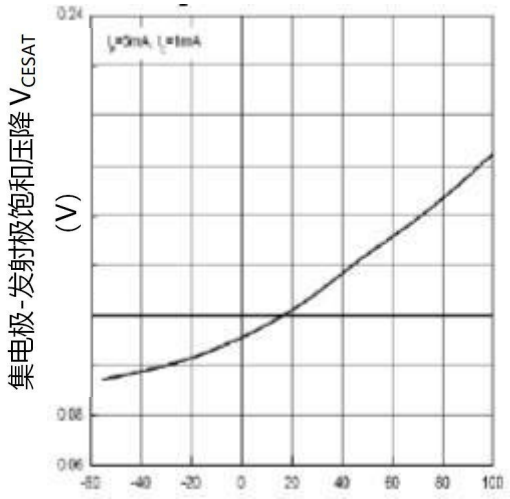
I_C-V_{CE}



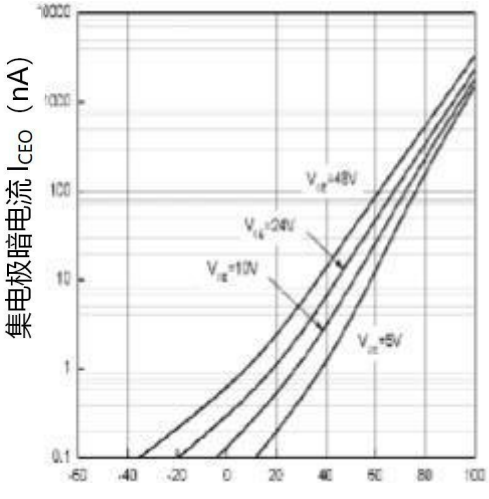
CTR-Ta



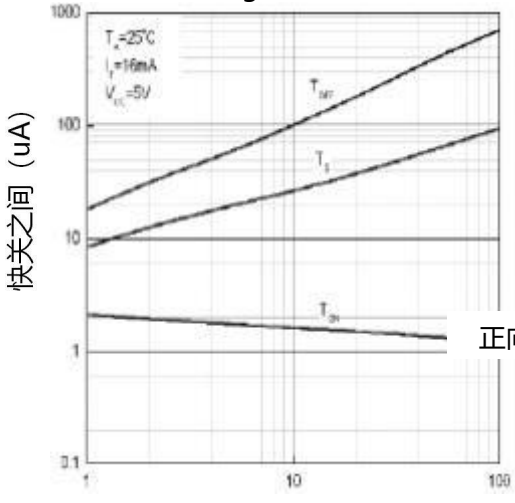
$V_{CE(SAT)}$-Ta



I_{CEO}-Ta

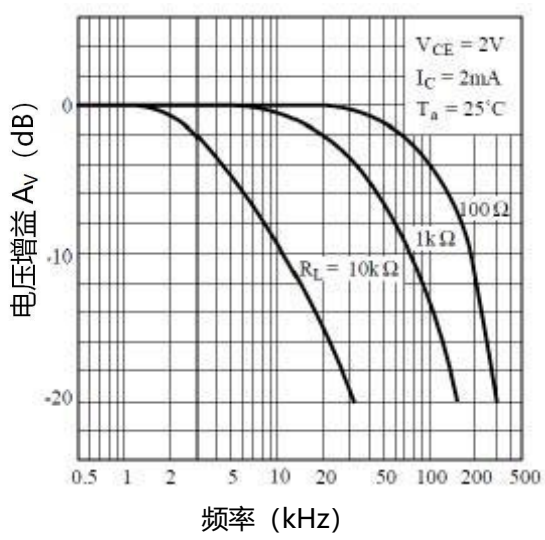


Switching Time-R_L

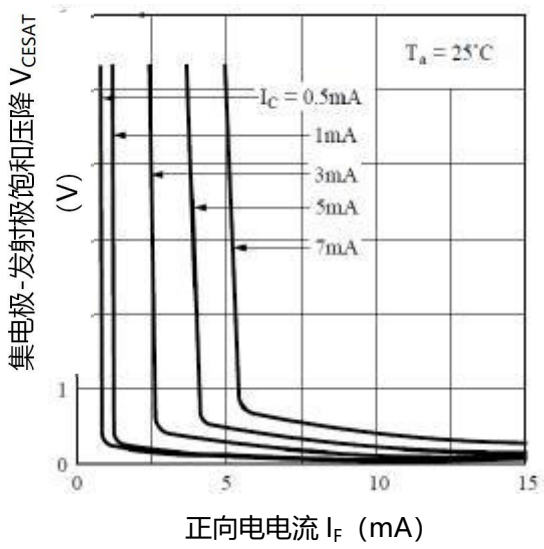


正向电压 V_F（V）

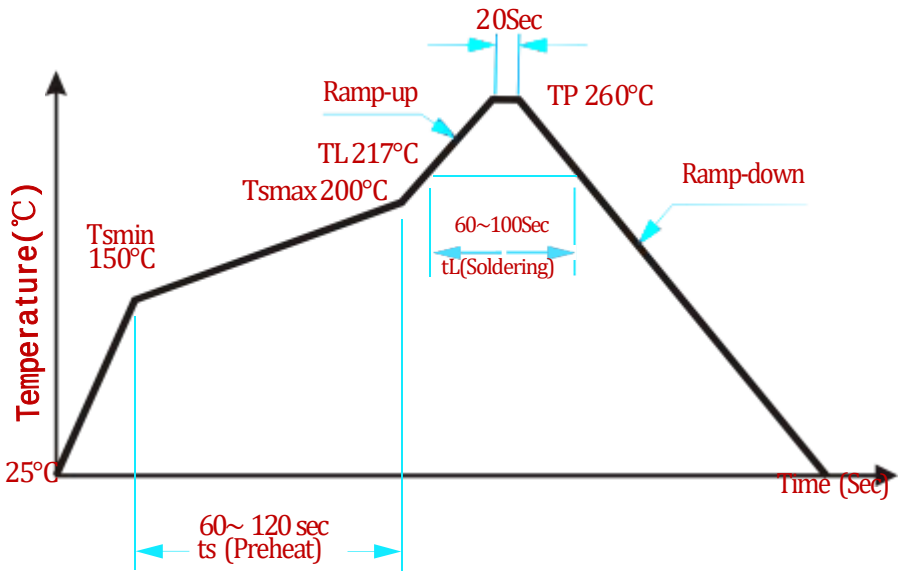
A_V-f



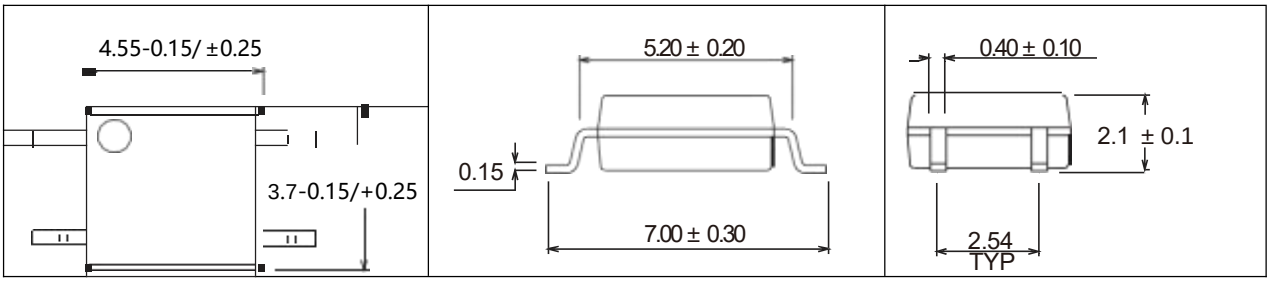
$V_{CE(SAT)}$-I_F



回流焊温度曲线图



外形尺寸



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